

	Type	Hits	Search Text	DBs	Time Stamp
1	BRS	5496	(Microelectromechanical adj Systems) or MEMS	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/10/31 13:44
2	BRS	1237	cleavage adj plane	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/03/17 17:13
3	BRS	11	((Microelectromechanical adj Systems) or MEMS) and (cleavage adj plane)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/04/03 12:56
4	BRS	72	((Microelectromechanical adj Systems) or MEMS) and cleavage) and orient\$5	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/03/17 17:50
5	BRS	40	((Microelectromechanical adj Systems) or MEMS) and cleavage) and orient\$5) and (opening or cavity)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/03/17 17:29
6	BRS	3	((Microelectromechanical adj Systems) or MEMS) and cleavage) and orient\$5) and wafer with (opening or cavity)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/03/17 17:40
7	BRS	130	((Microelectromechanical adj Systems) or MEMS) and cleavage	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/04/03 12:56
8	BRS	278	((Microelectromechanical adj Systems) or MEMS) and wafer with (opening or cavity)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/03/17 17:41
9	BRS	96	((Microelectromechanical adj Systems) or MEMS) and wafer with (opening or cavity)) and orient\$5	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/03/17 17:50
10	BRS	19	(photolithography same mask) and (etch\$3 same wafer) and (mask same angle same rotat\$3)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/03/18 13:25
11	BRS	14	(wafer same photolithography) and (photolithography same mask) and (etch\$3 same wafer) and (mask same angle same rotat\$3)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/03/18 14:06
12	BRS	1	(wafer same photolithography) and (photolithography same mask) and (etch\$3 same wafer) and (contact adj printing adj step)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/03/18 14:08
13	BRS	37	(wafer same photolithography) and (photolithography same mask) and (etch\$3 same wafer) and (contact adj printing)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/03/18 14:08
14	BRS	2584	((Microelectromechanical adj Systems) or MEMS) and wafer	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/04/03 13:00
15	BRS	11	((Microelectromechanical adj Systems) or MEMS) and (cleavage adj plane) and wafer	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/04/03 12:56

	Type	Hits	Search Text	DBs	Time Stamp
16	BRS	1378	((Microelectromechanical adj Systems) or MEMS) and micromachined	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/04/03 13:02
17	BRS	891	((Microelectromechanical adj Systems) or MEMS) and micromachined and wafer	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/04/03 13:02
18	BRS	31	((Microelectromechanical adj Systems) or MEMS) and micromachined and wafer and cleavage	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/04/03 13:03
19	BRS	1805	Microelectromechanical adj Systems	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/10/31 13:44